

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Byung-Duk LEE	12/24/2008
RECEIVING PARTY DATA	
Name:	Hynix Semiconductor Inc.
Street Address:	San 136-1, Ami-ri, Bubal-eup
City:	Icheon-si, Gyeonggi-do
State/Country:	REPUBLIC OF KOREA
Postal Code:	467-701
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13325851
CORRESPONDENCE DATA	
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Correspondent Name:	LOWE HAUPTMAN HAM & BERNER, LLP
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Address Line 2:	SUITE 300
Address Line 4:	ALEXANDRIA, VIRGINIA 22314
ATTORNEY DOCKET NUMBER:	123037-0059DIV
NAME OF SUBMITTER:	Yoon S. Ham
Total Attachments: 1 source=123037-0059_Assignment#page1.tif	

OP \$40.00 13325851

501756005

PATENT
REEL: 027381 FRAME: 0118

Docket No.: _____

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- | | |
|-------------------|----|
| 1) LEE, Byung-Duk | 2) |
| 3) | 4) |
| 5) | 6) |

who has made a certain new and useful invention, hereby sells, assigns and transfers unto **Hynix Semiconductor Inc.** having a place of business at San 136-1, Ami-ri, Bubal-eup, Icheon-si, Gyeonggi-do 467-701, Republic of Korea, its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

FUSE PART IN SEMICONDUCTOR DEVICE AND METHOD
FOR FORMING THE SAME

- (a) for which an application for United States Letters Patent was filed on _____, and identified by United States Patent Application No. _____, or
- (b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer all interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

- | | |
|---|-----------------------------------|
| 1) <u>Lee Byung-Duk</u>
Name: LEE, Byung-Duk | <u>December 24, 2008</u>
Date: |
| 2) _____
Name: | _____
Date: |
| 3) _____
Name: | _____
Date: |
| 4) _____
Name: | _____
Date: |